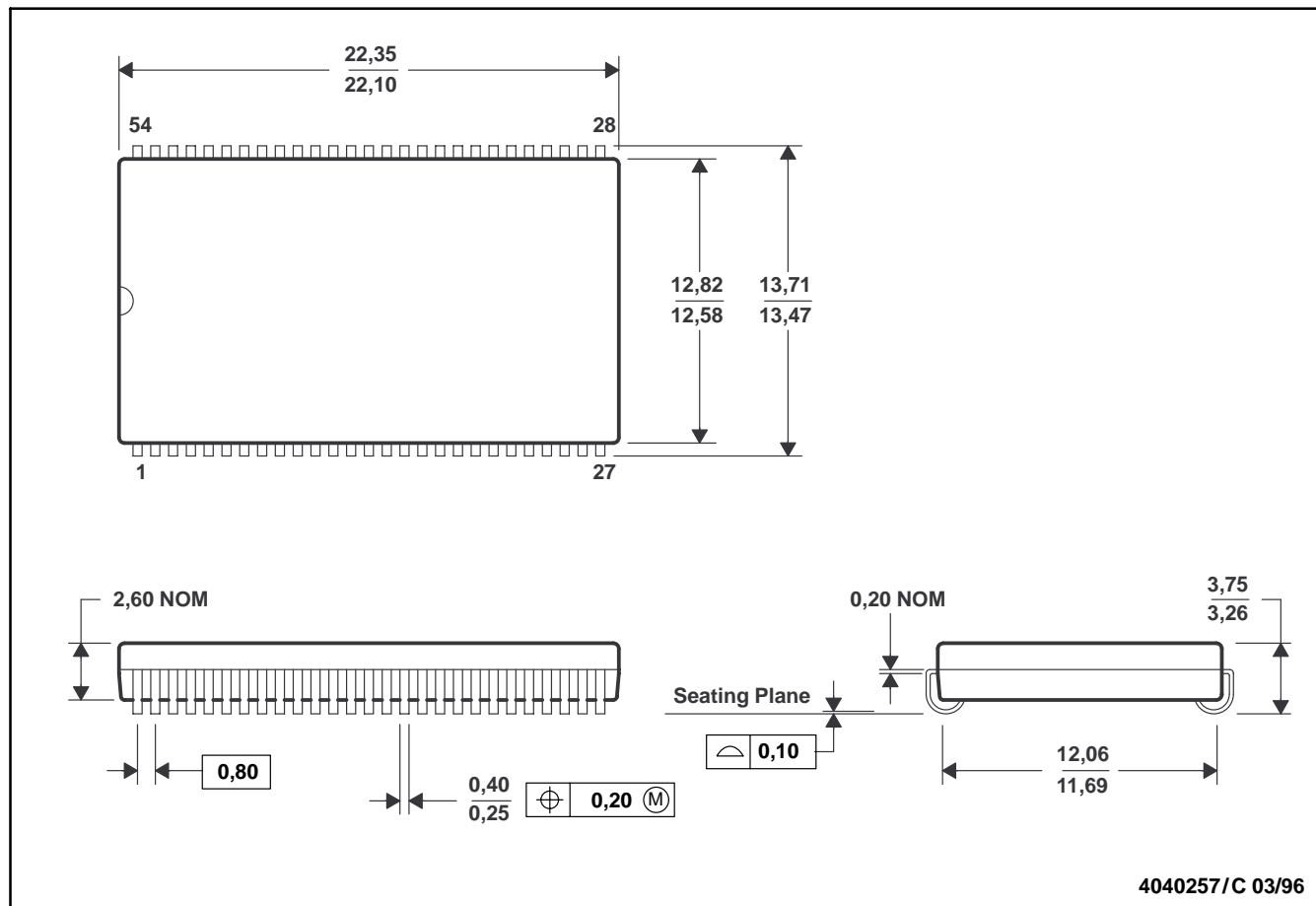


## DBH (R-PDSO-J54)

## PLASTIC SMALL-OUTLINE J-LEAD PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Plastic body dimensions do not include mold protrusion. Maximum mold protrusion is 0.28.

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